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## **Airspan and Qualcomm are Cooperating to Develop Integrated 5G Relay Backhaul**

BOCA RATON, Fla.--(BUSINESS WIRE)-- Airspan Networks Inc. is excited to announce today that it will be expanding its relationship with Qualcomm Technologies, Inc., a subsidiary of Qualcomm Incorporated, to include development and commercialization of 5G-NR relay for backhaul, using the Qualcomm® Snapdragon™ X50 5G modem.

By addressing key deployment barriers of Base Stations such as site acquisition and backhaul, Airspan has successfully delivered close to half a million 4G cells worldwide to customers such as Sprint, Reliance Jio, Softbank, and APT. Airspan's award winning integrated wireless access and backhaul portfolio, which includes AirUnity ("Magic Box"), AirDensity & AirSpeed will now support 5G-NR relay backhaul based on the integration with the Snapdragon X50 5G modem.

Airspan's world first, truly scalable platform, continues its innovation leadership into the 5G era, by supporting 5G-NR backhaul. This will allow operators to quickly monetize their 5G networks, even before consumers switch over to 5G devices. Thus improving customer experience while supporting data-hungry applications that continue to drive exponential increase in wireless data consumption.

"As global 5G networks and mobile devices are expected to become a commercial reality in 2019, operators immediately reap the benefit of using solutions like Airspan's 5G "Magic Box" – an independent, easy to install unit, that provides 4G access with all the benefits of being connected to the high capacity & low latency 5G network for backhaul" said Eli Leizerovitz, Head of Products at Airspan Networks.

"We are pleased to be working with an industry leader like Airspan to expand their small cell portfolio with groundbreaking 5G NR capabilities. With the Qualcomm® FSM™ 4G Small Cell Platform and the Snapdragon X50 5G modem for 5G mmWave and sub-6 GHz backhaul we're excited to see Airspan unveil a flexible and powerful 5G-enabled small cell solution" said Gautam Sheoran, Senior Director, Product Management at Qualcomm Technologies, Inc.

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*Qualcomm Snapdragon and Qualcomm FSM are products of Qualcomm Technologies, Inc. and/or its subsidiaries.*

### **About Airspan**

Airspan is a multi-award winning 4G & 5G network densification solution provider with an expansive product portfolio of indoor and outdoor, compact Femto, Pico, Micro and Macro base stations. The perfect tool kit to exploit the full potential of technologies such as

mmWave, Sub 6GHz, Massive MIMO and open V-RAN architectures. As well as an industry leading fixed wireless access and backhaul solution portfolio for PTP and PTMP applications.

Oak Investment Partners holds a controlling interest in Airspan. Airspan is not subject to the informational reporting requirements of the Securities Exchange Act of 1934 and, accordingly, does not file reports, financial statements, proxy statements, information statements or other information with the Securities and Exchange Commission. This press release contains forward-looking statements. For information about forward looking statements [www.airspan.com/fls](http://www.airspan.com/fls).

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